

LIST OF PUBLICATIONS CITED BY APPLICANT			<u>Atty Docket No.</u> SEL 239		<u>Serial No.</u> 09/782,239	
			<u>Applicant</u> Toshimitsu KONUMA et al			
			<u>Filing Date</u> February 13, 2001		<u>Group</u> 2814	
U.S. PATENT DOCUMENTS						
*EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUB- CLASS	FILING DATE
DAE	5,895,228	04/20/99	Biebuyck et al	438	99	03/20/97
FOREIGN PATENT DOCUMENTS						
	DOCUMENT NUMBER	DATE	APPLICANT	English Abstract	English Trans.	FILING DATE
	JP 07-258410	10/09/95	UBE Ind. Ltd.	X		03/18/94
	EP 0 768 352	04/16/97	Hitachi Chem Co.			06/30/95
	EP 0 881 668 A2	12/02/98	Dow Corning Toray Silicone Co. Ltd.			05/27/98
	EP 0 893 485	01/27/99	Sumitomo Chem Co.			07/22/98
	EP 0 899 987	03/03/99	TDK Corp.			08/28/98
OTHER PRIOR ART - NON PATENT LITERATURE DOCUMENTS						
(Include name of author (in CAPITAL LETTERS), title of article or item (book, magazine, journal, serial, symposium, catalog, etc.) date, pages(s), volume-issue number(s), publisher, city and/or country where published).						
	1) European Search Report re application no. EP 03 02 0964, mailed December 3, 2003. 2) FRITSCH, U. et al, "A Submicron CMOS Two Level Metal Process with Planarization Techniques," V-MIC Conf., June 13-14, 1988 IEEE, pp. 69-75 (1988). 3) IBARAKI, N. et al, "A New a-Si TFT with SiO ₂ /SiN _x Gate Insulator for 10.4 inch LCDs," Proceedings of the International Display Research Conference, IEEE, pp. 97-100, (1991). 4) PRAMANIK, D. et al, "A High Reliability Triple Metal Process for High Performance Application Specific Circuits," VLSI Multilevel Interconnection Conference, June 11-12, 1991, pp. 27-33, (1991).					
EXAMINER: <i>Douglas Will</i>				DATE CONSIDERED: <i>30 Aug 04</i>		
*EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP form. Draw line through citation if not in conformance and not considered. Include a copy of this form with the next communication to applicant.						